SPECIFICATION
FOR
LCM Module
KD050WVFLA022-C020A

ISO9001:2008 ISO/TS16949:2009

MODULE:	KD050WVFLA022-C020A
CUSTOMER:	

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* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 5.0'TFT-LCD contains 800X480 pixels, and can display up to 65K/262K/16.7M colors.

* Features

-Low Input Voltage: 3.3V(TYP)

-Display Colors of TFT LCD: 65K/262K/16.7M colors

TFT Interface: 6/8BIT LVDS

CTP Interface: I2C

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	108.0(H) *64.80(V) (5.0inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K/16.7M	colors	-
Number of pixels	800(RGB)*480	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.135(H) x 0.135 (V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	HX8678C/HX8249A	-	-
CTP Driver IC	GT911		
Display mode	Transmissive/Normally Black	-	-
Touch mode	5 points and Gestures		
Operating temperature	-30～+85	℃	-
Storage temperature	-40～+90	℃	-

* Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		124.90		mm	-
	Vertical(V)		78.10		mm	-
	Depth(D)		4.38		mm	-
Weight			TBD		g	-

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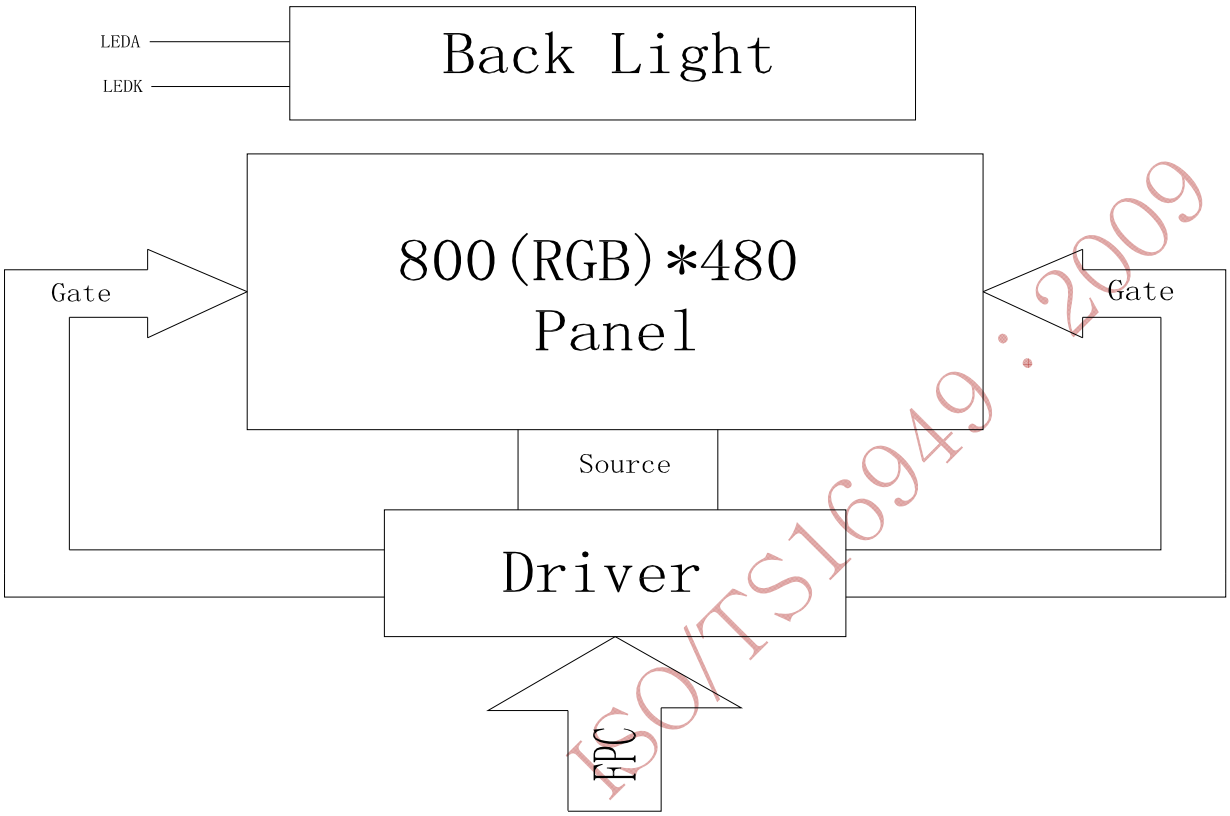
1. Block Diagram



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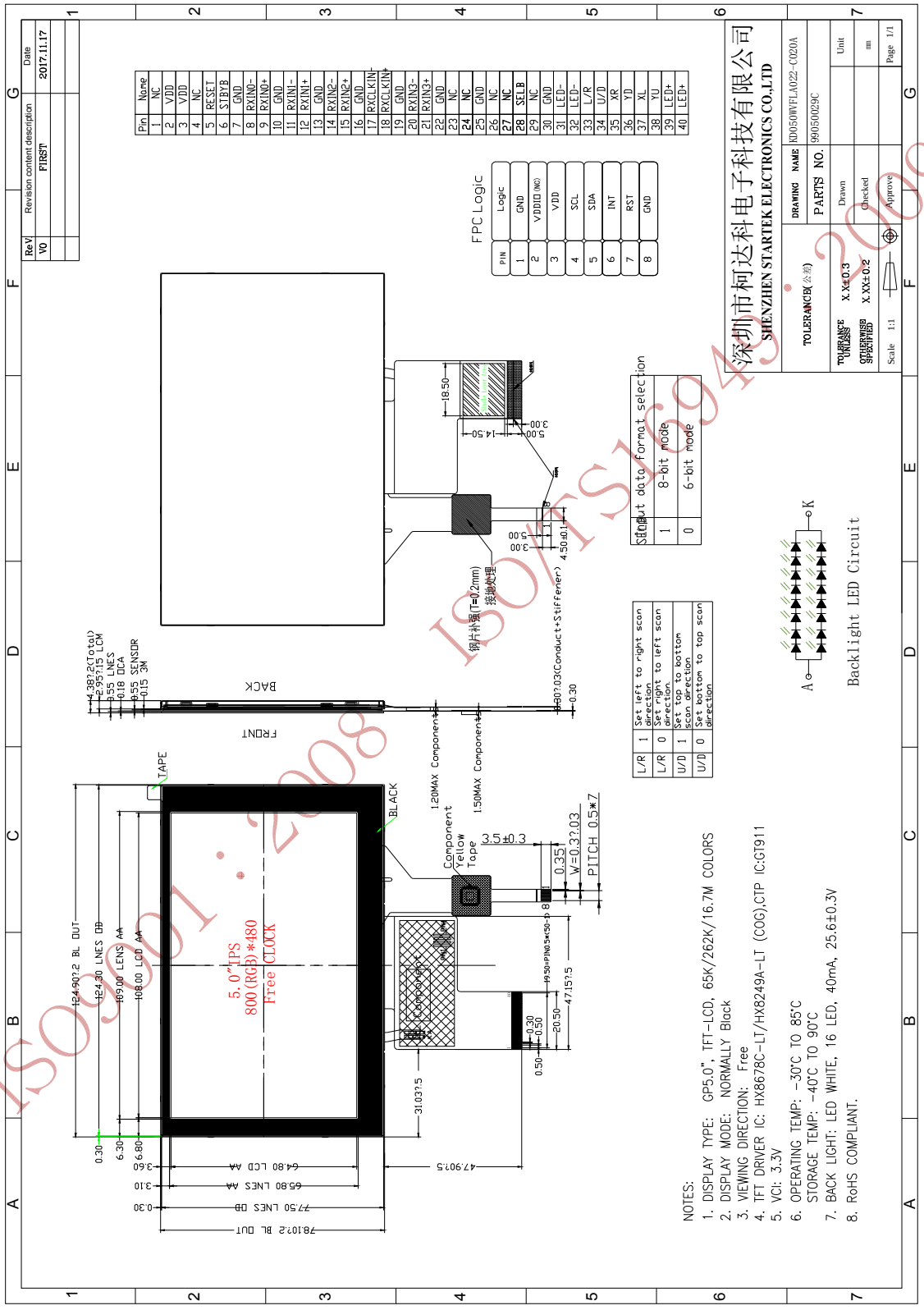
2. Outline dimension



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3. Input terminal Pin Assignment

3.1 TFT

NO.	SYMBOL	DISCRIPTION	I/O
1	NC		
2	VDD	Supply voltage(3.3V).	P
3	VDD	Supply voltage(3.3V).	P
4	NC		
5	RESET	Reset pin. The chip is in reset state when RESETB=0.	I
6	STBYB	Standby mode setting pin. The chip is in standby mode when STBYB=0.	I
7	GND	Ground.	P
8	RXIN0-	- LVDS differential data input	I
9	RXIN0+	+ LVDS differential data input	I
10	GND	Ground.	P
11	RXIN1-	- LVDS differential data input	I
12	RXIN1+	+ LVDS differential data input	I
13	GND	Ground.	P
14	RXIN2-	- LVDS differential data input	I
15	RXIN2+	+ LVDS differential data input	I
16	GND	Ground.	P
17	RXCLKIN-	- LVDS differential clock input	I
18	RXCLKIN+	+ LVDS differential clock input	I
19	GND	Ground.	P
20	RXIN3-	- LVDS differential data input	I
21	RXIN3+	+ LVDS differential data input	I
22	GND	Ground.	P
23	NC		
24	NC		

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25	GND	Ground.	P
26	NC		
27	NC		
28	SLEB	Input data format selection. SLEB=0, 6-BIT SLEB=1, 8-BIT	I
29	NC		
30	GND	Ground.	I
31	LED-	LED Cathode	P
32	LED-	LED Cathode	P
33	L/R	Horizontal shift direction (source output) selection(NOTE1)	I
34	U/D	Vertical shift direction (gate output) selection(NOTE1)	I
35	XR(NC)	Touch panel Right Glass Terminal	A/D
36	YD(NC)	Touch panel Bottom Film Terminal	A/D
37	XL(NC)	Touch panel LIFT Glass Terminal	A/D
38	YU(NC)	Touch panel Top Film Terminal	A/D
39	LED+	LED Anode	P
40	LED+	LED Anode	P

3.2 CTP

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	NC		
3	VDD	Supply voltage.	P
4	SCL	I2C clock input.	I
5	SDA	I2C data input and output	I/O
6	INT	External interrupt to the host.	I
7	RST	External Reset, Low is active.	I
8	GND	Ground.	P

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4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	Θ=0 Normal viewing angle	--	1000	--		2
Response time	Rising	$T_{R+}T_F$		--	35	40	msec	3
	Falling			--				
Color gamut		S(%)		--	65.84	--	%	
Color Filter Chromacicity	White	W_X		0.275	0.325	0.365		
		W_Y		0.326	0.366	0.406		
	Red	R_X		0.579	0.619	0.659		
		R_Y		0.306	0.346	0.386		
	Green	G_X		0.286	0.326	0.366		
		G_Y		0.585	0.625	0.665		
	Blue	B_X		0.105	0.145	0.185		
		B_Y		0.045	0.085	0.125		
Viewing angle	Hor.	Θ_L	CR>10	--	85	--		
		Θ_R		--	85	--		
	Ver.	Θ_U		--	85	--		
		Θ_D		--	85	--		
Option View Direction		Free						

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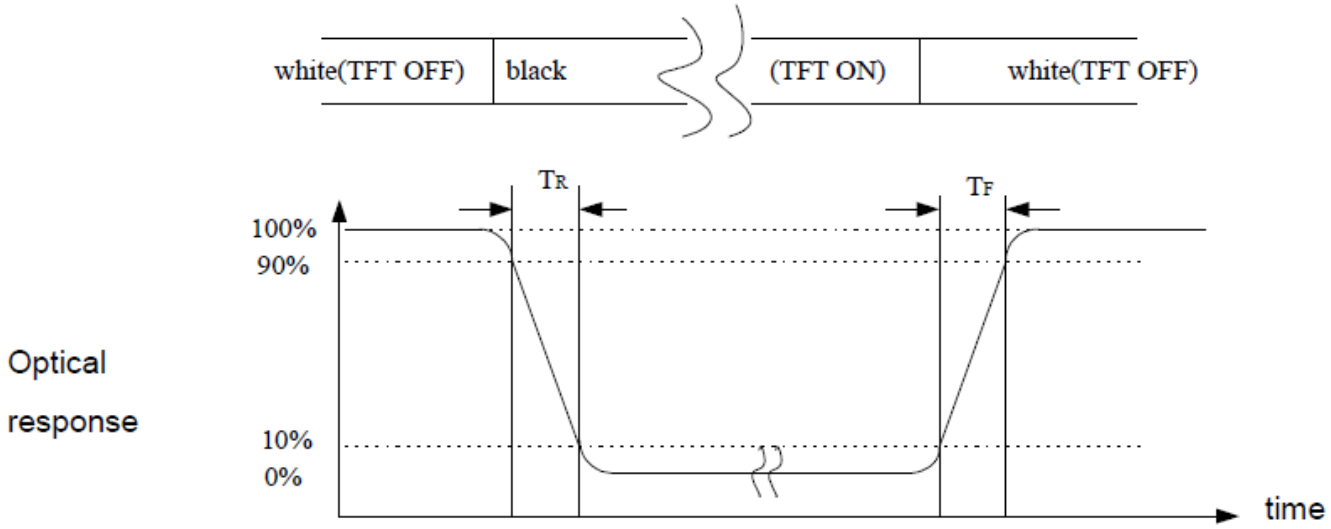
Note (2) Definition of Contrast Ratio (CR) :
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3) Definition of Response Time : Sum of T_R and T_F



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5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.0	**V**
Operating temperature	T_{OP}	-30	+85	℃
Storage temperature	T_{ST}	-40	+90	℃

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	3.0	3.3	3.6	V	
Normal mode Current consumption	IDD	--	65	--	mA	
Level input voltage	V_{IH}	0.7V_{DD}	-	VDD	V	
	V_{IL}	GND	-	0.3V_{DD}	V	
Level output voltage	V_{OH}	0.8VDD	-	VDD	V	
	V_{OL}	GND	-	0.2VDD	V	

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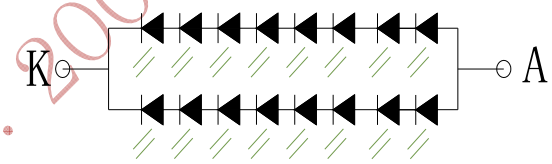
5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 16 chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	30	40	--	mA	
Forward Voltage	V_F	--	25.6	--	V	
LCM Luminance	L_V	580	630	--	cd/m2	Note3
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	Note3

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=40mA. The LED lifetime could be decreased if operating IL is larger than 40mA. The constant current driving method is suggested.



Backlight LED Circuit

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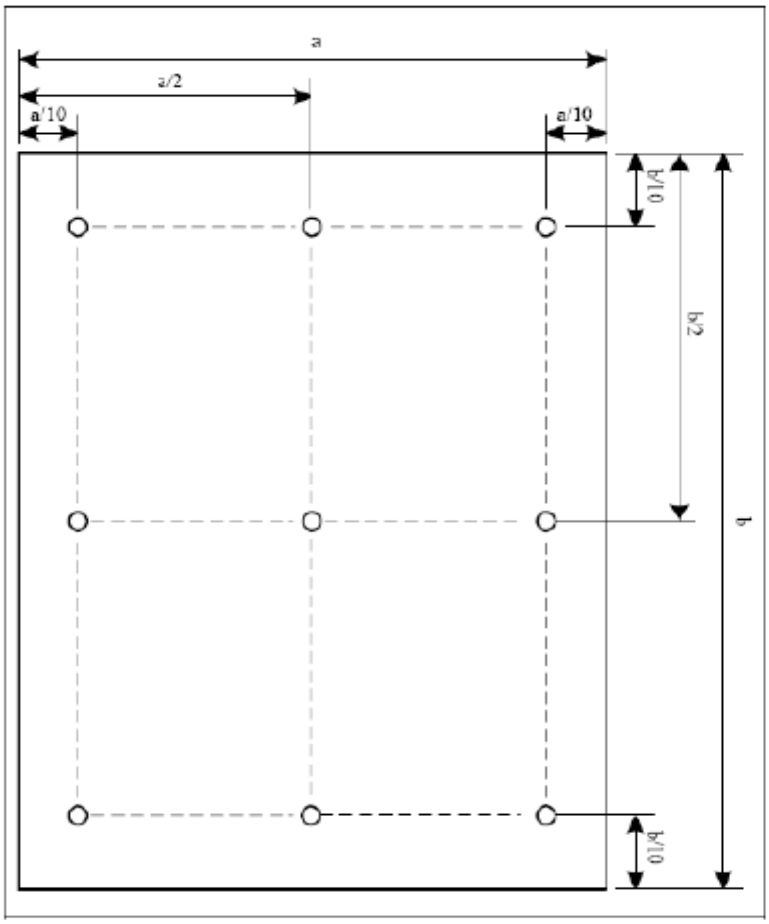
NOTE 3：Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

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6. AC Characteristic

6.1 LVDS 6-bit vs. 8-bit mode

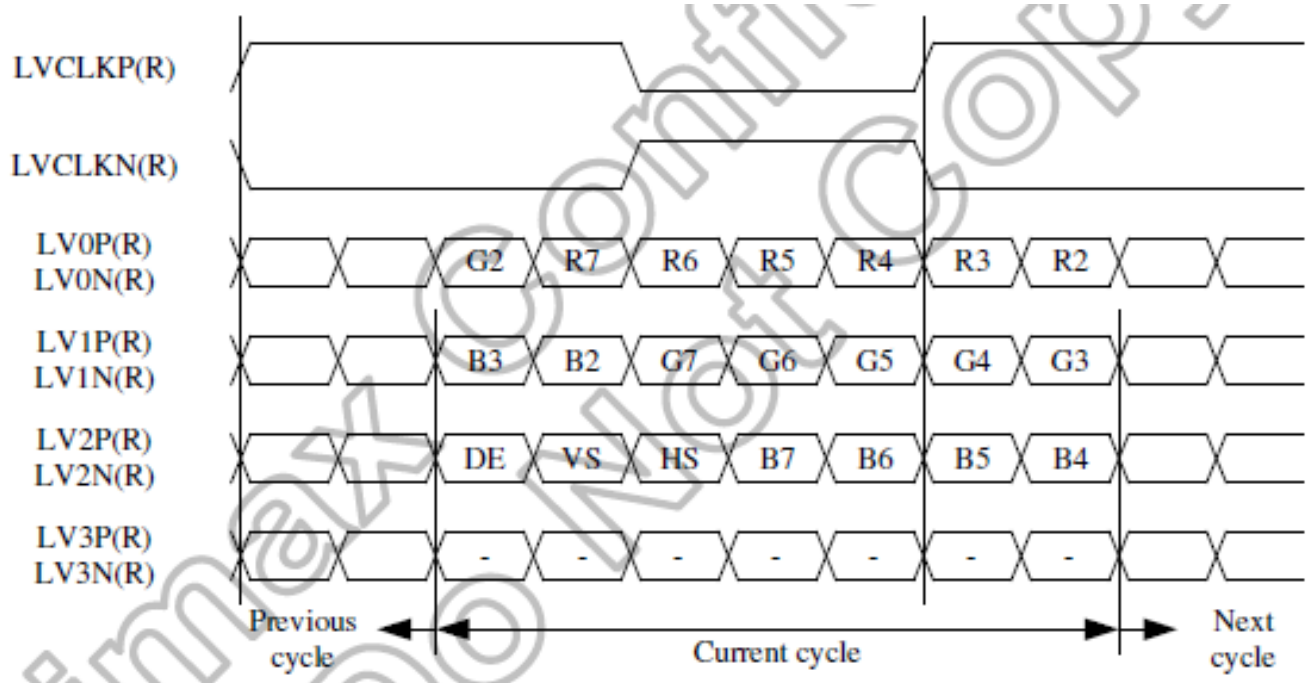

Figure 4.1: LVDS 6-bit

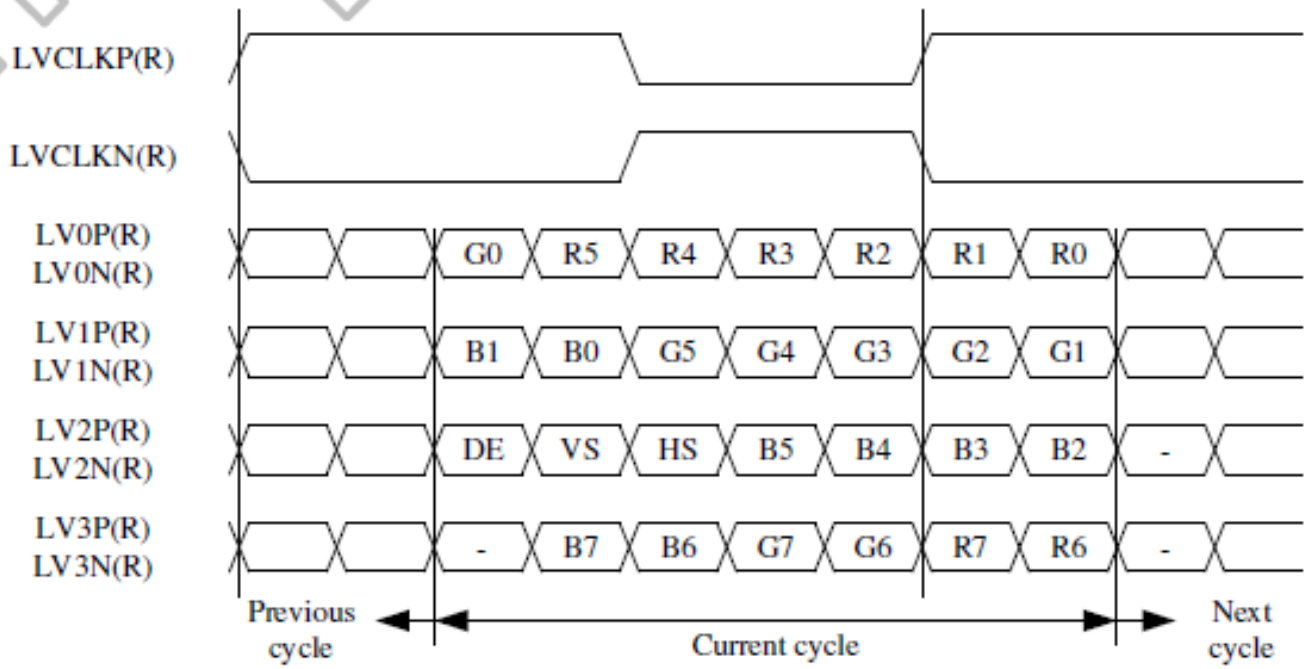

Figure 4.2: LVDS 8-bit (VESA format)

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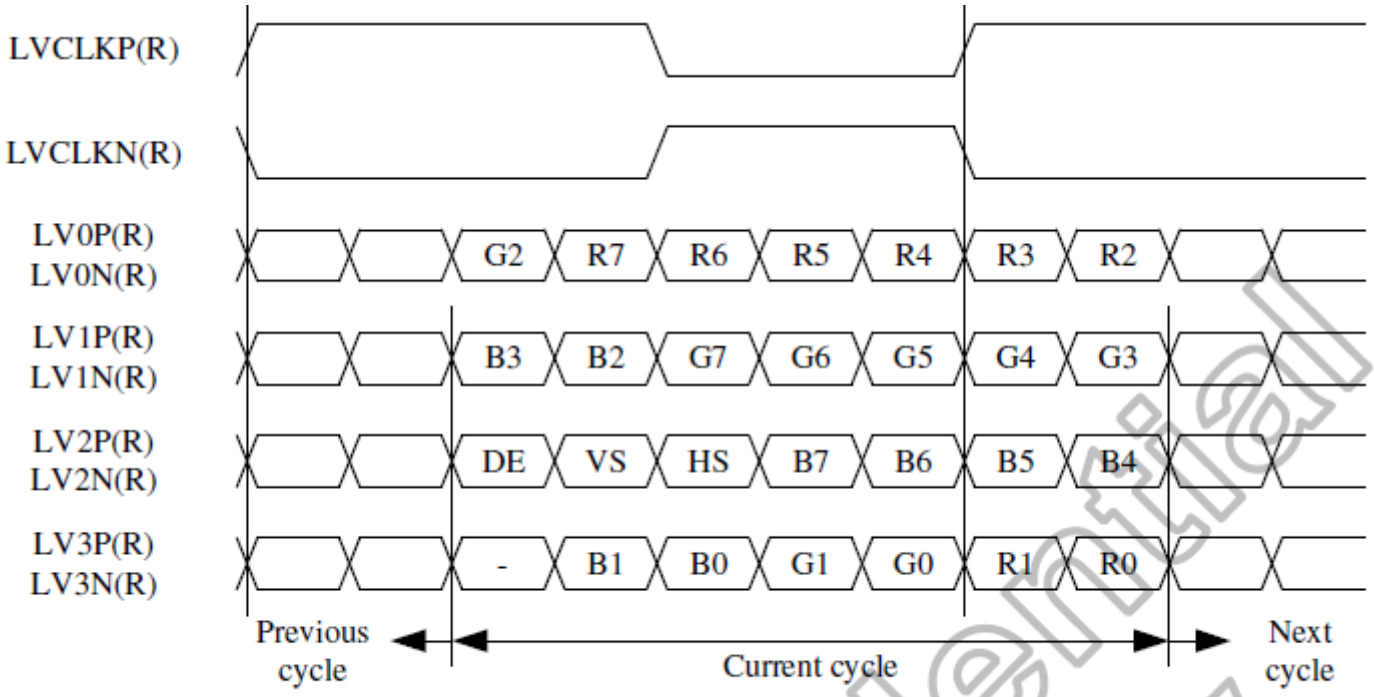

Figure 4.3: LVDS 8-bit (JEIDA format)

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6.2 LVDS input timing

LVDS input timing is described as below.

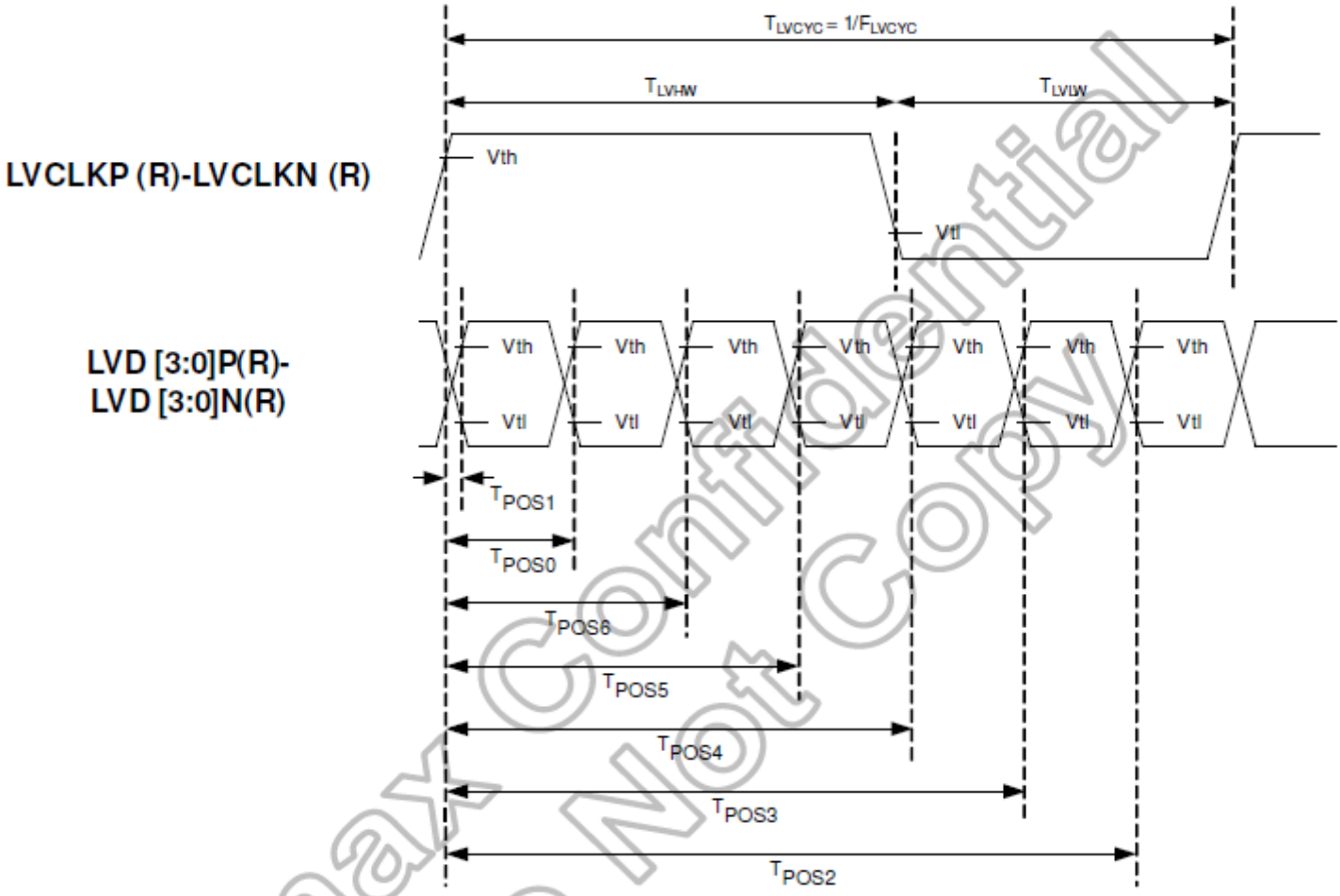

Figure 7.2: LVDS input timing

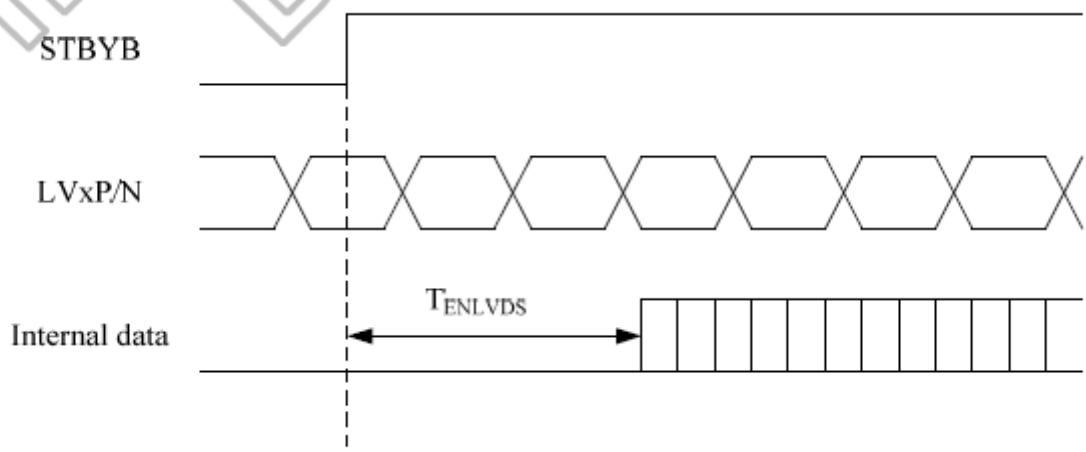

Figure 7.3: LVDS wake up time

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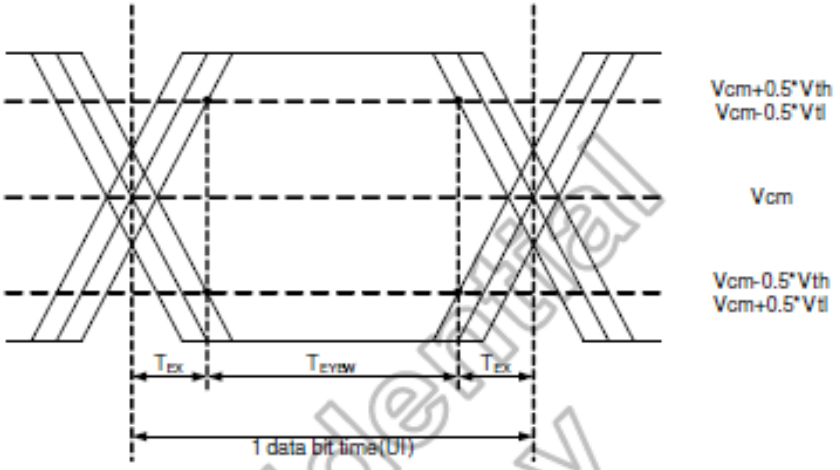
Single-ended:
LVD [3:0]P,
LVD [3:0]N



Differential:
LVD [3:0]P-LVD [3:0]N

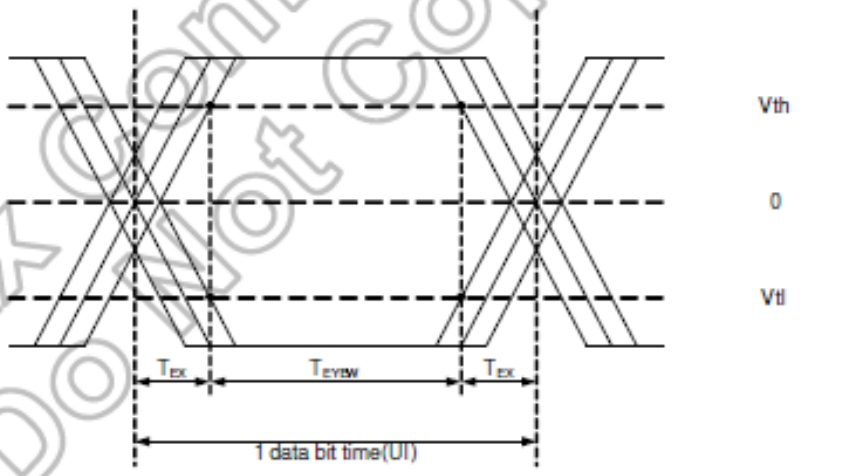


Figure 7.4: LVDS input eye diagram

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Parameter	Symbol	Spec. Min.	Spec. Typ.	Spec. Max.	Unit
Clock frequency	FLVCYC	10	-	85	MHz
Clock period	TLVCYC	11.76	-	100	nsec
1 data bit time	UI	-	1/7	-	TLVCYC
Clock high time	LVHW	2.9	4	4.1	UI
Clock low time	LVLW	2.9	3	4.1	UI
Position 1	TPOS1	-0.2	0	0.2	UI
Position 0	TPOS0	0.8	1	1.2	UI
Position 6	TPOS6	1.8	2	2.2	UI
Position 5	TPOS5	2.8	3	3.2	UI
Position 4	TPOS4	3.8	4	4.2	UI
Position 3	TPOS3	4.8	5	5.2	UI
Position 2	TPOS2	5.8	6	6.2	UI
Input eye width	TEYEW	0.6	-	-	UI
Input eye border	TEX	-	-	0.2	UI
LVDS wake up time	TENLVDS	-	-	150	µs

Table 7.2: LVDS input timing parameters

6.3 Reset timing

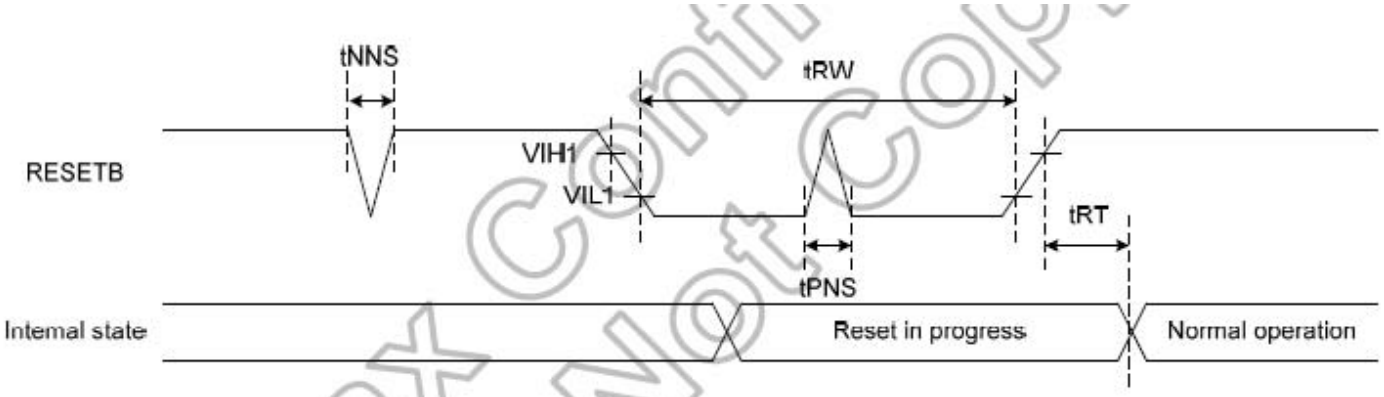

Figure 7.5: Reset timing

(VDD1=VDD2=2.7 to 3.6V, GND=0V, T_A=-40 to +95 °C)

Signal	Paramete	Symbol	Spec.			Unit
			Min.	Typ.	Max.	
RESETB	Reset pulse width	tRW	10	-	-	μs
	Reset complete time	tRT	-	-	5	μs
	Positive spike noise width	tPNS	-	-	100	ns
	Negative spike noise width	tNNS	-	-	100	ns

Table 7.4: Reset timing parameters

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7. CTP Specification

7.1 Electrical Characteristics

7.1.1 Absolute Maximum Rating

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VDD	2.66	3.47	V	--
Operating temperature	TOP	-30	+85	℃	--
Storage temperature	TST	-40	+90	℃	--

7.1.2 DC Electrical Characteristics (Ta=25℃)

(Ambient temperature:25℃, AVDD=2.8V, VDDIO=1.8V or VDDIO=AVDD)

Item	Min.	Typ.	Max.	Unit	Note
Normal mode operating current	--	8	14.5	mA	
Green mode operating current	--	3.3	--	mA	
Sleep mode operating current	70	--	120	uA	
Doze mode operating current	--	0.78	--	mA	
Digital Input low voltage/VIL	-0.3	--	0.25*VDD	V	
Digital Input high voltage/VIH	0.75*VDD	--	VDD+0.3	V	
Digital Output low voltage/VOL	--		0.15*VDD	V	
Digital Output high voltage/VOH	0.85*VDD			V	

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7.1.3 AC Characteristics

(Ambient temperature:25℃, AVDD=2.8V, VDDIO=1.8V)

Parameter	Min	Typ	Max	Unit
OSC oscillation frequency	59	60	61	MHZ
I/O output rise time,low to high	-	14	-	ns
I/O output rfall time,high to low	-	14	-	ns

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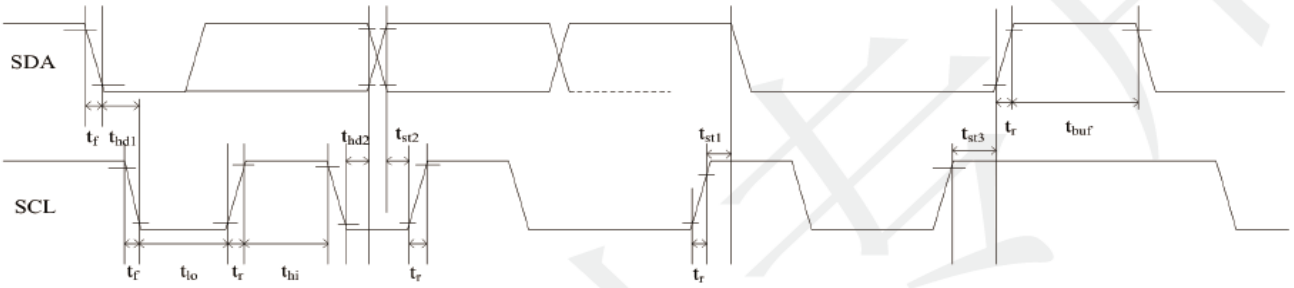
7.2 I2C Timing

GT911 provides a standard I2C interface for SCL and SDA to communicate with the host. GT911 always serves as slave device in the system with all communication being initialized by the host. It is strongly recommended that transmission rate be kept at or below 400Kbps. The I2C timing is shown below:



Test condition 1: 1.8V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

Test condition 2: 3.3V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

GT911 supports two I2C slave addresses: 0xBA/0xBB and 0x28/0x29. The host can select the address by changing the status of Reset and INT pins during the power-on initialization phase. See the diagram below for configuration methods and timings:

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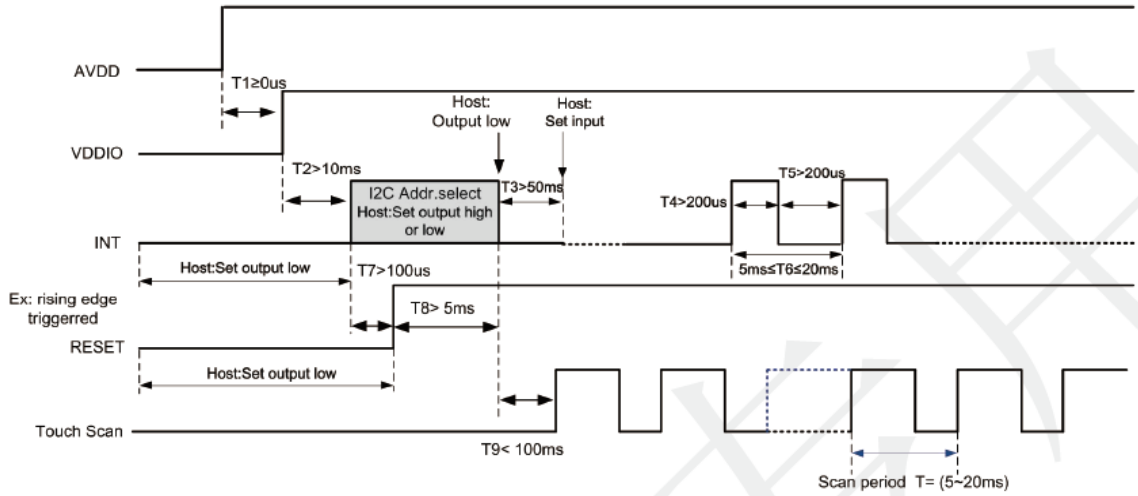
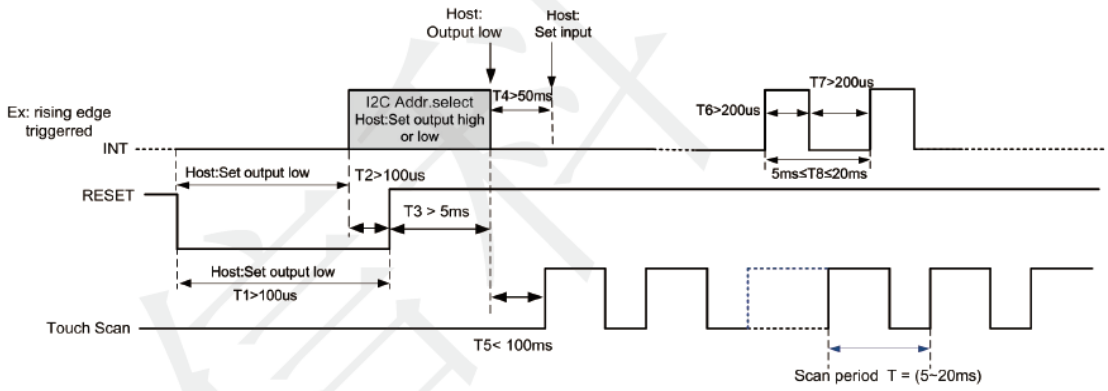
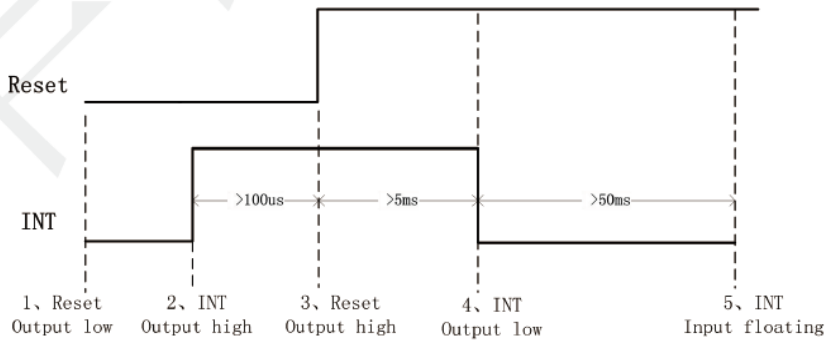
Power-on Timing:



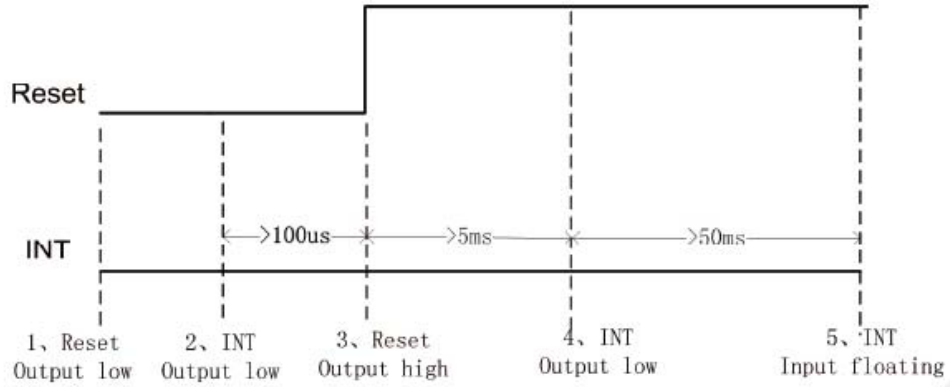
Timing for host resetting GT911:



Timing for setting slave address to 0x28/0x29:



Timing for setting slave address to 0xBA/0xBB:



a) Data Transmission

(For example：device address is 0xBA/0xBB)

Communication is always initiated by the host. Valid Start condition is signaled by pulling SDA line from "high" to "low" when SCL line is "high". Data flow or address is transmitted after the Start condition.

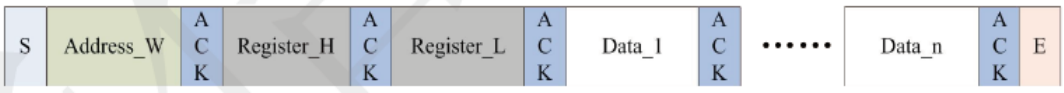
All slave devices connected to I²C bus should detect the 8-bit address issued after Start condition and send the correct ACK. After receiving matching address, GT911 acknowledges by configuring SDA line as output port and pulling SDA line low during the ninth SCL cycle. When receiving unmatched address, namely, not 0XBA or 0XBB, GT911 will stay in an idle state.

For data bytes on SDA, each of 9 serial bits will be sent on nine SCL cycles. Each data byte consists of 8 valid data bits and one ACK or NACK bit sent by the recipient. The data transmission is valid when SCL line is "high".

When communication is completed, the host will issue the STOP condition. Stop condition implies the transition of SDA line from "low" to "high" when SCL line is "high".

b) Writing Data to GT911

(For example：device address is 0xBA/0xBB)



Timing for Write Operation

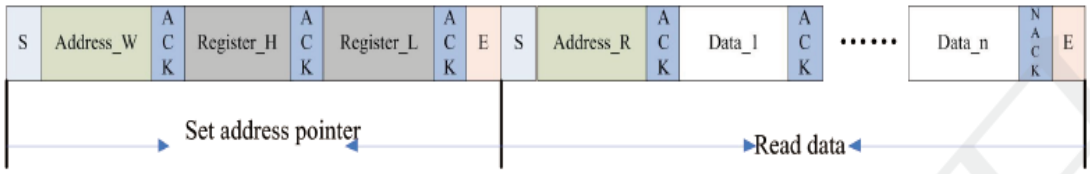
The diagram above displays the timing sequence of the host writing data onto GT911. First, the host issues a Start condition. Then, the host sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where writing starts) and the 8-bit data bytes (to be written onto the register).

The location of the register address pointer will automatically add 1 after every Write Operation. Therefore, when the host needs to perform Write Operations on a group of registers of continuous addresses, it is able to write continuously. The Write Operation is terminated when the host issues the Stop condition.

c) Reading Data from GT911

(For example：device address is 0xBA/0xBB)



Timing for Read Operation

The diagram above is the timing sequence of the host reading data from GT911. First, the host issues a Start condition and sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where reading starts) to the slave device. Then the host sets register addresses which need to be read.

Also after receiving ACK, the host issues the Start condition once again and sends 0XBB (Read Operation). After receiving ACK, the host starts to read data.

GT911 also supports continuous Read Operation and, by default, reads data continuously. Whenever receiving a byte of data, the host sends an ACK signal indicating successful reception. After receiving the last byte of data, the host sends a NACK signal followed by a STOP condition which terminates communication.

8. LCD Module Out-Going Quality Level

8.1 VISUAL & FUNCTION INSPECTION STANDARD

8.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

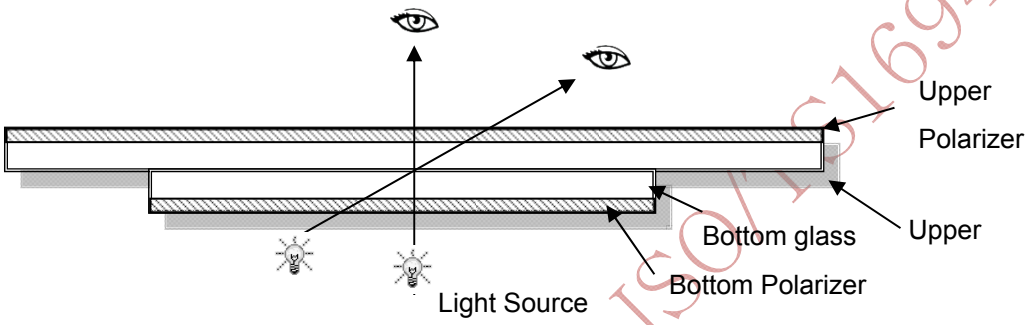
Temperature : 25±5℃

Humidity : 65%±10%RH

Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



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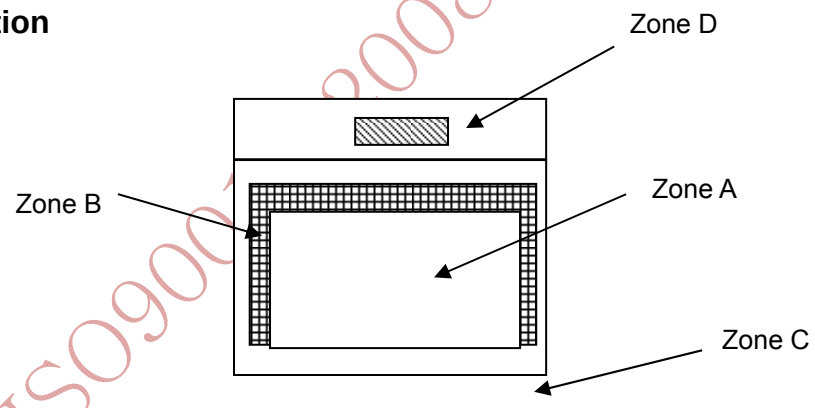
8.1.2 Definition



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Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C Cover (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note:As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

8.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class Ⅱ

AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot Line defect	Light dot , Dim spot , Polarizer Bubble ; Polarizer accidented spot.	
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

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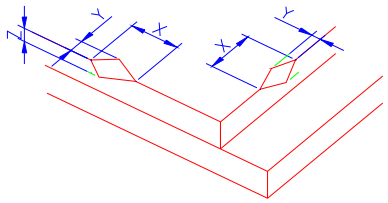
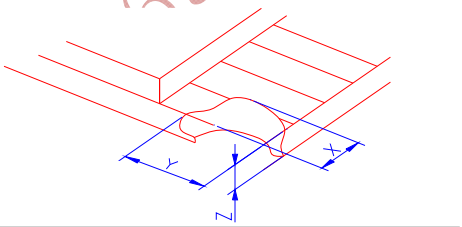
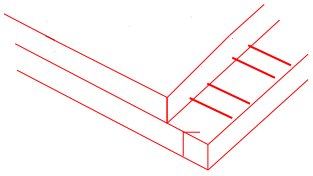
8.1.4 Criteria (Visual)

<table>
<tr><th>Number</th><th>Items</th><th>Criteria(mm)</th></tr>
<tr><td rowspan="3">1.0 LCD Crack/Broken
NOTE:
X: Length
Y: Width
Z: Height
L: Length of ITO,
T: Height of LCD</td><td>(1) The edge of LCD broken</td><td> 
<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr>
</table></td></tr>
<tr><td>(2)LCD corner broken</td><td> 
<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr>
</table></td></tr>
<tr><td>(3) LCD crack</td><td> 
Crack
Not allowed</td></tr>
</table>

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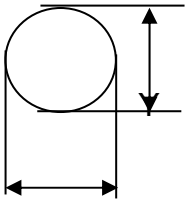
2.0

Spot defect



X

Φ=(X+Y)/2

① light dot（LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain）

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.10	Ignore		Ignore
0.10<Φ≤0.25	4(distance≧10mm)		
0.25<Φ≤0.35	3		
Φ>0.4	0		

②Dim spot（LCD/TP/Polarizer dim dot, light leakage、dark spot）

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.1	Ignore		Ignore
0.10<Φ≤0.25	4(distance≧10mm)		
0.25<Φ≤0.35	3		
Φ>0.4	0		

③ Polarizer accidented spot

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.3<Φ≤0.5	3(distance≧10mm)		
Φ>0.5	1		

④Pixel bad points（light dot，Dim dot, color dot）

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.15	Ignore		Ignore
0.2<Φ≤0.3	2(distance≧10mm)		
Φ>0.4	1		

⑤ Polarizer Bubble

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.3<Φ≤0.4	4(distance≧10 m)		
0.4<Φ≤0.5	3		
Φ>0.5	1		

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<table>
<tr><td>3.0</td><td>Line defect (LCD/TP /Polarizer backlight black/white line, scratch, stain)</td><td>
<table>
<tr><td rowspan="2">Width(mm)</td><td rowspan="2">Length(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.05</td><td>Ignore</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.05<W≤0.06</td><td>L≤4.0</td><td colspan="2">N≤3</td></tr>
<tr><td>0.07<W≤0.08</td><td>L≤3.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.08<W</td><td colspan="4">Define as spot defect</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>Electronic Components SMT</td><td>Not allow missing parts，solderless connection，cold solder joint，mis match，The positive and negative polarity opposite</td></tr>
<tr><td>5.0</td><td>Display color& Brightness</td><td>1. Color：Measuring the color coordinates, The measurement standard according to the datasheet or samples.
2. Brightness：Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.</td></tr>
<tr><td rowspan="2">6.0</td><td rowspan="2">CTP Related</td><td>CTP Cover sensor accidented black/white spot</td><td>
<table>
<tr><td rowspan="2">Size Φ(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.15<Φ≤0.25</td><td colspan="2">4（distance≧10mm）</td></tr>
<tr><td>0.25<Φ≤0.35</td><td colspan="2">3</td></tr>
<tr><td>Φ>0.4</td><td colspan="2">1</td><td></td></tr>
</table>
</td></tr>
<tr><td>CTP Cover scratch</td><td>
<table>
<tr><td rowspan="2">Width(mm)</td><td rowspan="2">Ignore(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.05</td><td>Ignore</td><td colspan="3">Ignore</td></tr>
<tr><td>0.05<W≤0.06</td><td>L≤4.0</td><td colspan="3">N≤3</td></tr>
<tr><td>0.07<W≤0.08</td><td>L≤3.0</td><td colspan="3">N≤2</td></tr>
<tr><td>0.08<W</td><td colspan="4">Define as spot defect</td></tr>
</table>
</td></tr>
</table>

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CTP Cover Pinhole/ Lack of ink

Zone / Size (mm)	Acceptable Qty
	C
Φ≤0.2	Ignore
0.2<Φ≤0.3	4(distance≧10mm)
0.3<Φ≤0.4	3
Φ>0.4	0

CTP Bonding bubble/ accidented spot

Size Φ(mm)	Acceptable Qty	
	A	B
Φ≤0.1	Ignore	
0.15<Φ≤0.2	3(distance≧10mm)	
0.2<Φ≤0.25	2	
Φ>0.25	0	

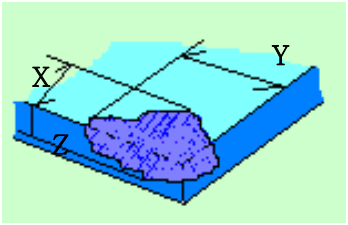
Assembly deflection

beyond the edge of backlight ≤0.2mm

TP cover broken
X：length
Y：width
Z：height

X	Y	Z
X≤0.5mm	Y≤0.5mm	Z<cover thickness

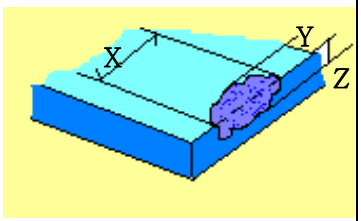
* Circuitry broken is not allowed.



TP cover broken
X：length
Y：width
Z：height

X	Y	Z
X≤0.3mm	Y≤0.3mm	Z<LCD thickness

* Circuitry broken is not allowed.



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Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

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9. Reliability Test Result

9.1 Condition

Item	Condition	Sample Size	Test Result	Note
Low Temperature Operating Life test	-30℃, 96HR	3ea	pass	-
Thermal Humidity Operating Life test	85℃90%RH, 96HR	3ea	pass	-
Temperature Cycle ON/OFF test	-30℃ ↔ 85℃, ON/OFF, 20CYC	3ea	pass	(1)
High Temperature Storage test	90℃, 96HR	3ea	pass	-
Low Temperature Storage test	－40℃, 96HR	3ea	pass	-
ESD test	150pF, 330Ω , ±6KV(Contact)/± 8KV(Air), 5 points/panel, 10 times/point	3ea	pass	
Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	3ea	pass	
Box Drop Test	1 Corner 3 Edges 6 faces, 66㎝(MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds

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10. Cautions and Handling Precautions

10.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.
Do not warp or twist the module during assembly work.
(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
(4) Do not allow drops of water or chemicals to remain on the display surface.
If you have the droplets for a long time, staining and discoloration may occur.
(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
(8) Protect the module from static; it may cause damage to the CMOS ICs.
(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
(10) Do not disassemble the module.
(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
(12) Pins of I/F connector shall not be touched directly with bare hands.
(13) Do not connect, disconnect the module in the “Power ON” condition.
(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

10.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.
It is highly recommended to store the module with temperature from 0 to 35 ℃ and relative humidity of less than 70%
(2) Do not store the TFT-LCD module in direct sunlight.
(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

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11. Packing

----TBD----------

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